

**■ Features**

- Molding Inductor.
- High reliability.
- High current, low DCR, high efficiency.
- Very low acoustic noise and very low leakage flux noise.
- Operating temperature: -55°C ~ +125°C (Including self-temperature rise) .

**■ Applications**

- General Electronic.
- Video Device, TV, TFT.
- Power Module for PC.
- NB/Lap Top Computer.
- Server, VGA Card/Module.
- DC/DC converter.

**■ Product Identification**



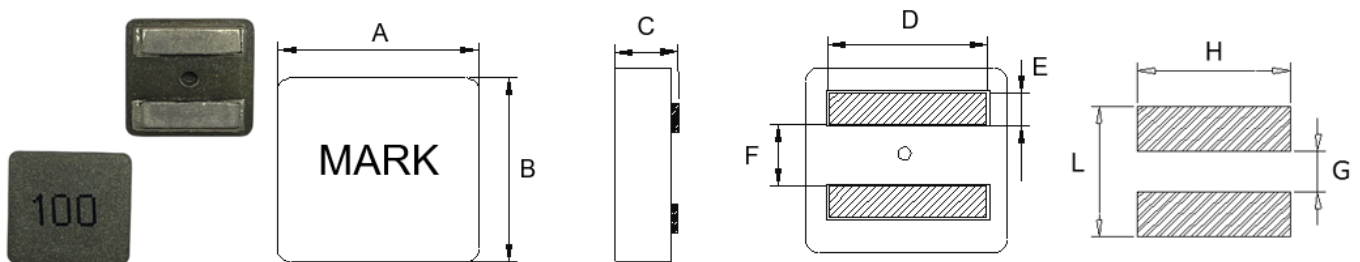
(1) : Type

(2) : Dimensions

(3) : Inductance value

(4) : Inductance Tolerance : N=±30%,M=±20%

**■ Shapes and Dimensions (Unit: mm)**



TYPE	A	B	C	D	E	F	G Ref.	H Ref.	L Ref.
YSPIT0530A	5.5±0.2	5.3±0.2	2.9±0.2	4.3±0.3	1.1±0.3	2.3±0.3	2.0	4.7	4.5

## ■ YSPIT0530A Series

Part Number	Inductance (uH) @100KHz/0.1V	DCR Max. (mΩ)	Saturation Current (A)		Heat Rating Current Typ.(A)	
			Max.	Typ.	20°C rise	40°C rise
YSPIT0530A-R15M	0.15±20%	2.4	32.5	36.0	14.3	22.2
YSPIT0530A-R16M	0.16±20%	2.4	32.0	35.0	14.2	22.2
YSPIT0530A-R33M	0.33±20%	3.6	26.0	28.0	13.8	19.2
YSPIT0530A-R47M	0.47±20%	4.2	24.0	26.0	13.7	18.4
YSPIT0530A-R56M	0.56±20%	4.6	20.2	22.2	13.6	17.7
YSPIT0530A-R60M	0.60±20%	4.6	20.0	22.0	13.6	17.7
YSPIT0530A-R80M	0.80±20%	5.7	18.0	20.0	10.1	13.1
YSPIT0530A-R82M	0.82±20%	5.8	17.6	19.7	9.9	12.9
YSPIT0530A-1R0M	1.0±20%	7.6	14.3	16.5	9.0	12.2
YSPIT0530A-1R2M	1.2±20%	9.7	13.5	15.0	8.5	11.0
YSPIT0530A-1R5M	1.5±20%	11.2	12.5	14.0	8.0	10.5
YSPIT0530A-1R8M	1.8±20%	12.7	11.3	12.3	7.6	10.1
YSPIT0530A-2R2M	2.2±20%	14.5	9.0	10.0	7.2	9.7
YSPIT0530A-3R3M	3.3±20%	23.1	8.7	9.5	5.9	8.1
YSPIT0530A-4R7M	4.7±20%	36.3	7.0	8.2	4.3	5.9

- ※ The saturation current value is the DC current value having inductance decrease down to 30%.(at 25°C)
- ※ The temperature rise current value is the DC current value having temperature increase up to 40°C. (at 25°C)
- ※ The rated current is the DC current value that satisfies both of current value saturation current value and temperature rise current value.

## ■ Mechanical Reliability

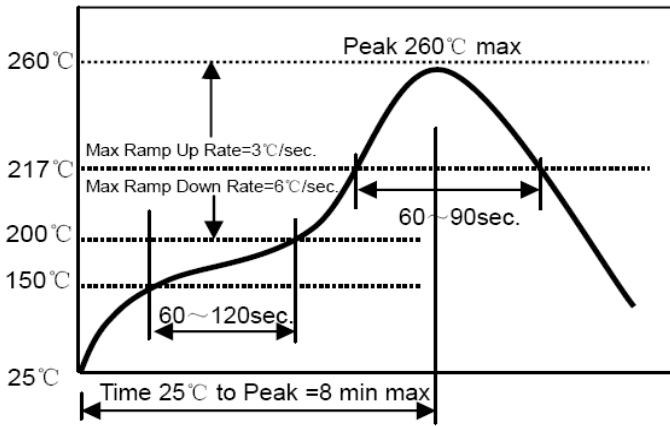
Item	Specification and Requirement	Test Method
Solderability	1. No case deformation or change in visual 2. New solder coverage More than 95%	1. Preheat : $155^{\circ}\text{C} \pm 5^{\circ}\text{C}$ , $60\text{S} \pm 2\text{S}$ 2. Tin: lead-free. 3. Temperature: $240^{\circ}\text{C} \pm 5^{\circ}\text{C}$ , flux $3.0\text{S} \pm 0.5\text{S}$ .
Mechanical shock	1. No case deformation or change in visual 2. $\Delta L/L_0 \leq \pm 10\%$	1. Acceleration : 100G 2. Pulse time: : 6ms 3. 3 times in each positive and negative direction of 3 mutual perpendicular directions
Mechanical vibration	1. No case deformation or change in visual 2. $\Delta L/L_0 \leq \pm 10\%$	1. Reflow: 2times 2. Frequency: 10HZ ~ 50HZ ~ 10HZ, 20 Min/Cycles 3. Amplitude: $1.52\text{ mm} \pm 10\%$ 4. Directions: X,Y,Z 5. Time: 12 cycle / direction

## ■ Endurance Reliability

Item	Specification and Requirement	Test Method
Thermal Shock	Inductance change: Within $\pm 10\%$ Without distinct damage in visual	1. First $-55^{\circ}\text{C}$ for 30 minutes, last $125^{\circ}\text{C}$ for 30 minutes as 1 cycle. Go through 1000 cycles. 2. Max transfer time is 3 minutes. 3. Measured at room temperature after placing for $24 \pm 2$ hours
Biased Humidity	Inductance change: Within $\pm 10\%$ Without distinct damage in visual	1. Reflow 2 times, $2.85^{\circ}\text{C} \pm 3^{\circ}\text{C}$ , $85\% \pm 3\% \text{RH}$ , 1000 hours 3. Measured at room temperature after placing for $24 \pm 2$ hours
Low temperature storage	Inductance change: Within $\pm 10\%$ Without distinct damage in visual	1. Temperature : $-55 \pm 2^{\circ}\text{C}$ 2. Time : 1000 hours 3. Measured at room temperature after placing for $24 \pm 2$ hours
High temperature storage	Inductance change: Within $\pm 10\%$ Without distinct damage in visual	1. Temperature : $+125 \pm 2^{\circ}\text{C}$ 2. Time : 1000 hours 3. Measured at room temperature after placing for $24 \pm 2$ hours

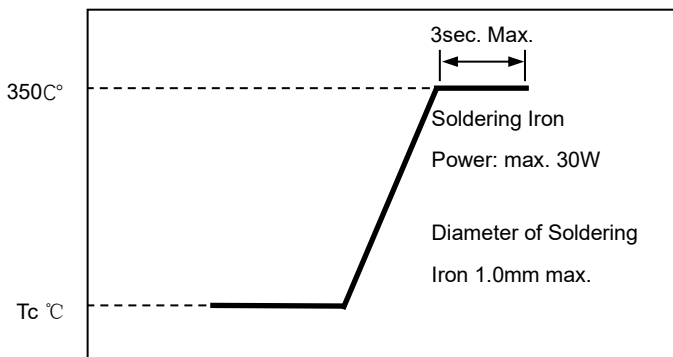
**Recommended Soldering Technologies**

**Re-flowing Profile**



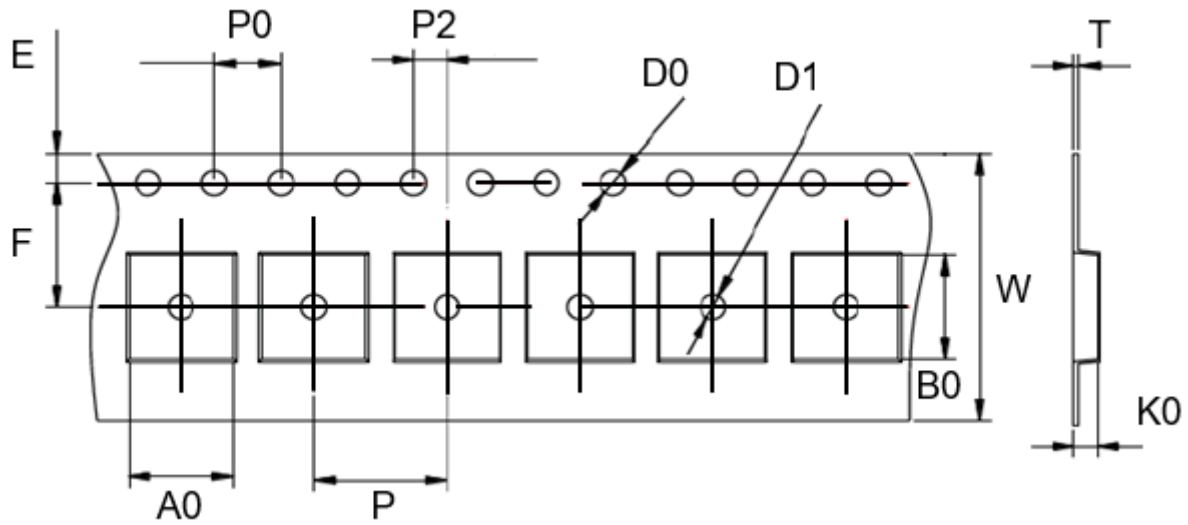
Preheat condition: 150 ~200°C/60~120sec.  
 Allowed time above 217°C: 60~90sec.  
 Peak temp: 260°C  
 Max time at Peak temp: 10 sec.  
 Solder paste: Sn/3.0Ag/0.5Cu  
 Allowed Reflow time: 2x max

**Iron Soldering Profile**



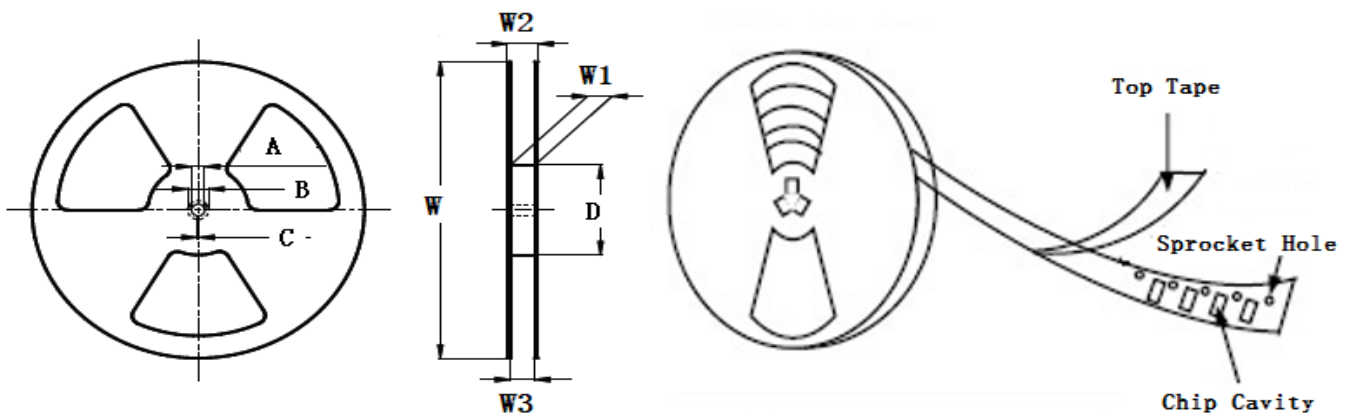
Iron soldering power: Max. 30W  
 Pre-heating: 150°C/60sec.  
 Soldering Tip temperature: 350°C Max.  
 Soldering time: 3sec. Max.  
 Solder paste: Sn/3.0Ag/0.5Cu  
 Max.1 times for iron soldering

**■ Taping Dimensions(Unit:mm)**



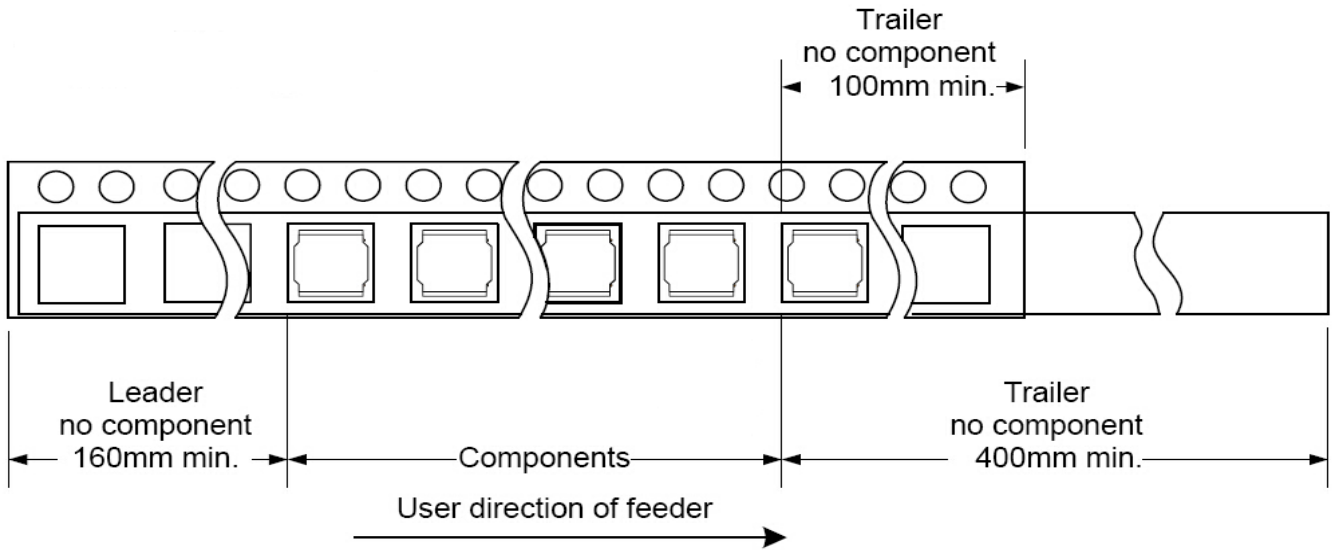
TYPE	W	P	P0	P2	D0	D1	T	A0	B0	K0	E	F	MPQ
YSPIT0530A	16.0 ±0.3	8.0 ±0.1	4.0 ±0.1	2.0 ±0.1	1.5 ±0.1	1.5 ±0.1	0.35 ±0.05	6.0 ±0.1	5.7 ±0.1	3.3 ±0.1	1.75 ±0.1	7.5 ±0.1	2000

**■ Reel Dimensions(Unit:mm)**

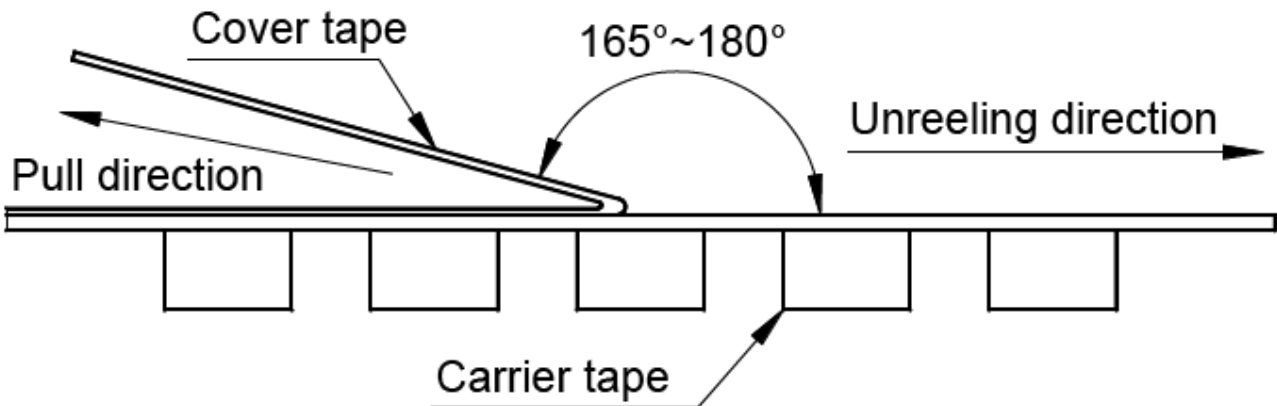


TYPE	W	W1	W2	W3	A	B	C	D
YSPIT0530A	330±2.0	12.4±2.0	18.4MAX	11.9 Min	13.0±0.5	21.0±0.8	2.0±0.5	97±0.5

**Direction of rolling**



**Cover tape peel off condition**



Cover tape peel force shall be 0.1N to 1.3N.

Reference peel speed 300±10mm/min.

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